

---

Application No.: 10/668881Case No.: 58053US005

---

**Amendments to the Specification:**

The Office Action states in part:

The disclosure is objected to because of the following informalities:

(a) On page 6, line 8 of Applicant's amendment, "region 1210a, 1210b, 1210c exists near the die corner 1200a, 1200b" should be -- regions 1210a, 1210b, 1210c exist near the die corners 1200a, 1200b, and 1200c --.

Appropriate correction is required.

Please amend the specification as follows:

On page 13, please replace the paragraph that starts on line 1 with the word "Finite" and ends on line 13 with the number "0.11%" with the following amended paragraph:

Finite element models can be used to determine the appropriate size of the solid planes. Figure 11 shows results from a model of a 40 mm square package with an 18.5 mm die and a 1.0 mm thick lid with several die-stiffener spacings (3 mm (Fig. 11a), 5 mm (Fig. 11b), and 7 mm (Fig. 11c)). A high strain region 1210a, 1210b, 1210c exists near the die corner 1200a, 1200b, 1200c where the strain is greater than the critical strain at which cracking will occur. An aspect of the invention herein disclosed allows the means to adjust the area of, and locate the position of, a solid plane where a geometric discontinuity would cause a crack to form during assembly, testing, or use of the final interconnect module. The edges of the solid plane preferably extend beyond the high strain region because the edges of the solid plane themselves are discontinuities that could initiate cracks if the critical strain is exceeded. For the purposes of this particular analysis, the critical strain level was set at a value equal to 1/3 of the 95% confidence interval on the experimental fracture strain for MICROLAM dielectric material or 0.11%.